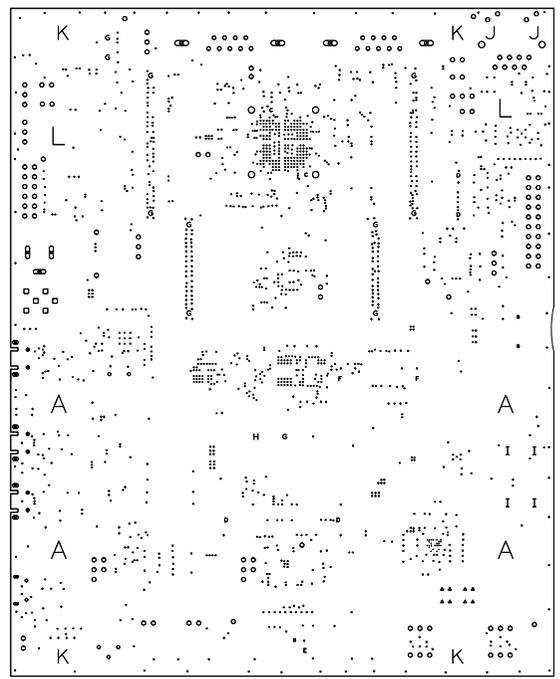


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1.0	EDITION ORIGINALE	2008-**-**	***

5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,6 4	5.0 4.0	N/A	55 OHM	N/A	+/-10%
1 4	5.1 4.1	9.9 10.9	N/A	100 OHM	+/-10%
1,6 4	6.1 5.1	8.9 9.9	N/A	90 OHM	+/-10%

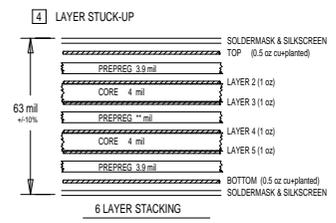


DRILL CHART: TOP TO BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	ROTATION	QTY
-	6.0	+3.0/-3.0	PLATED	-	24
-	8.0	+3.0/-3.0	PLATED	-	404
-	10.0	+3.0/-3.0	PLATED	-	640
-	12.0	+3.0/-3.0	PLATED	-	581
o	30.0	+3.0/-3.0	PLATED	-	5
*	33.0	+3.0/-3.0	PLATED	-	2
▲	36.0	+3.0/-3.0	PLATED	-	8
o	38.0	+3.0/-3.0	PLATED	-	18
o	40.0	+3.0/-3.0	PLATED	-	116
□	48.0	+3.0/-3.0	PLATED	-	6
o	64.0	+3.0/-3.0	PLATED	-	6
△	177.0	+3.0/-3.0	PLATED	-	4
*	28.0	+2.0/-2.0	NON-PLATED	-	3
c	33.46	+2.0/-2.0	NON-PLATED	-	2
d	38.0	+2.0/-2.0	NON-PLATED	-	4
e	39.0	+2.0/-2.0	NON-PLATED	-	1
f	40.0	+2.0/-2.0	NON-PLATED	-	2
g	47.0	+2.0/-2.0	NON-PLATED	-	11
h	58.0	+2.0/-2.0	NON-PLATED	-	1
i	79.0	+2.0/-2.0	NON-PLATED	-	4
j	125.0	+2.0/-2.0	NON-PLATED	-	2
k	138.0	+2.0/-2.0	NON-PLATED	-	4
l	177.0	+2.0/-2.0	NON-PLATED	-	2
•	33.0x30.0	+5.0/-5.0	PLATED	0.000	6
•	51.0x24.0	+5.0/-5.0	PLATED	0.000	2
•	59.0x33.0	+5.0/-5.0	PLATED	0.000	6
⊗	126.0x40.0	+5.0/-5.0	PLATED	90.000	2
⊗	126.0x40.0	+5.0/-5.0	PLATED	0.000	1
⊗	140.0x50.0	+5.0/-5.0	PLATED	0.000	4

TOTAL HOLES: 1871



- PCB SPECIFICATIONS:**
- A. MATERIAL: FR-4, TG-170 TG-150 TG-140
 - B. MATERIAL FAMILY: N/A.
 - C. SOLDERMASK COLOR: GREEN BLUE RED BLACK
 - D. SILKSCREEN COLOR: WHITE YELLOW BLACK
 - E. SURFACE FINISH: ENIG IMMERSION SILVER IMMERSION TIN
 HASL HASL(PB-FREE) GOLDEN FINGER
- IMPEDANCE CONTROL: NO YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- G. THROUGH VIA: PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL: SOLDERMASK NON-CONDUCTIVE EPOXY.
- STACK-UP: SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.
- PCB REQUIREMENTS:**
- THIS BOARD WILL CONFORM TO:
IPC-A-600, CURRENT REV., CLASS II
IPC-6012, CURRENT REV., CLASS II
 - UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.
ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION.
 - PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 BY COROSS SECTION.
 - MATERIAL FR4 RATING 94V-0 MINIMUM EPOXY GLASS LAMINATE.
 - BOARD SHALL BE LPI SOLDER MASKED OVER BARE COPPER BOTH SIDES PER IPC-SM-840 CLASS II.
 - SILKSCREEN SHALL BE PERMANENT NON-CONDUCTIVE INK AND WITH NO OVERLAP ON ANY COMPONENT PAD OR THROUGH HOLE.
 - MFGR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK
A. U.L. CODE D. MFGR. LOGO
B. DATE CODE E. SUCCESSFUL ELECTRICAL BOARD TEST.
C. FLAMMABILITY RATING
 - REMOVE THE FLASHS WHICH SMALLER THAN HOLE SIZE.
 - REMOVE ALL SHAPE EDGES AND BURRS .005 MAXIMUM.
 - PLEASE USE THE SUPPLIED IPC 356 NETLIST TO VERIFY BOARD BEFORE FABRICATING BOARD.

<p>DESIGNED BY SOFER www.sofer.com.cn Tel : +86 21-6482 6908 Mail: design@sofer.com.cn</p>	LAYER: FAB DAWNING & DRILL LEGEND	COMPANY NAME: ST
	DESIGNER: Shelley	PROJECT NAME: MB1246
	DATE: 2016.08.11	PROJECT NUMBER: D031-020A2
		REV B

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS + 3 PL DECIMALS + ANGLES + FRACTIONS +	SIGNATURES	DATE	LOGO	COMPANY NAME
	DRAWN	YY-MM-DD		
	CHECKED	YY-MM-DD	TITLE PROJECT NAME *	
	ENGRG	YY-MM-DD	SIZE B	DWG NO *****
ISSUED		SCALE 1:1	SHEET	1 OF 1

